

**PMP2829 Rev B Bill Of Materials**

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C1, C2, C3	3	3.3uF	CAP, CERM, 50V, +/-10%, X7R, 1210	1210	STD	STD
C4	1	0.1uF	CAP, CERM, 100V, +/-10%, X7R, 1206	1206	STD	STD
C5, C6, C8, C16	4	22uF	CAP, CERM, 16V, +/-10%, X7R, 1210	1210	STD	STD
C7	1	330uF	CAP, OS-CON, 330uF, 16V, +/-20%, 0.016 ohm, 10x10.3 SMD	10x10.3	16SVP330M	Sanyo
C9, C17	2	330pF	CAP, CERM, 50V, +/-10%, X7R, 0603	0603	STD	STD
C14	1	10pF	CAP, CERM, 50V, +/-10%, X7R, 0603	0603	STD	STD
C19	1	100pF	CAP, CERM, 50V, +/-10%, X7R, 0603	0603	STD	STD
C20	1	0.022uF	CAP, CERM, 50V, +/-10%, X7R, 0603	0603	STD	STD
C21	1	10uF	CAP, CERM, 16V, +/-10%, X7R, 1210	1210	STD	STD
C22	1	0.047uF	CAP, CERM, 25V, +/-10%, X7R, 0603	0603	STD	STD
C100	1	1000pF	CAP, CERM, 1000pF, 1000V, +/-10%, X7R, 1808	1808	STD	STD
D1	1	60V	Diode, Schottky, 60V, 20A, DDPAK	DDPAK	MBRB2060CTT4G	ON Semiconductor
D2	1	1.25V	DIODE ULTRA FAST 100V 2A SMB	SMB	MURS110T3G	ON Semi
D3, D7, D100	3	75V	Diode, Ultrafast, 75V, 0.3A, SOT-23	SOT-23	BAS16-7-F	Diodes Inc.
J1, J2	2		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm	ED555/2DS	On-Shore Technology
L1	1	1uH	Inductor, Shielded Drum Core, Ferrite, 1uH, 5.39A, 0.0099 ohm, SMD	DR74	DR74-1R0-R	Coiltronics
Q1	1	100V	MOSFET, N-CH, 100V, 16A, SON 5x6mm	SON 5x6mm	CSD19531Q5A	Texas Instruments
R1	1	20k	RES, 1%, 0.125W, 0805	0805	STD	STD
R2	1	10k	RES, 1%, 0.125W, 0805	0805	STD	STD
R3	1	20	RES, 1%, 0.33W, 1210	1210	STD	STD
R4, R100	2	0	RES, 1%, 0.1W, 0603	0603	STD	STD
R5, R19, R25	3	1k	RES, 1%, 0.1W, 0603	0603	STD	STD
R6	1	0.05	RES, 1%, 1W, 2512	2512	STD	STD
R9, R20, R21	3	10k	RES, 1%, 0.1W, 0603	0603	STD	STD
R11	1	4.99k	RES, 1%, 0.1W, 0603	0603	STD	STD
R13	1	49.9	RES, 1%, 0.1W, 0603	0603	STD	STD
R14	1	4.99	RES, 1%, 0.1W, 0603	0603	STD	STD
R17	1	20k	RES, 1%, 0.1W, 0603	0603	STD	STD
R18	1	3.01k	RES, 1%, 0.1W, 0603	0603	STD	STD
R24	1	2.61k	RES, 1%, 0.1W, 0603	0603	STD	STD
T1	1	9uH	Transformer, 9uH, TH	1050x550x1050mil	PA2261NL	Pulse Engineering
TP1, TP3, TP7	3	Red	Test Point, Miniature, Red, TH	Red Miniature Testpoint	5000	Keystone
TP2, TP4	2	Black	Test Point, Miniature, Black, TH	Black Miniature Testpoint	5001	Keystone
U1	1		Low Power Current Mode Push-Pull PWM with Current Control, 50 % Duty Cycle, -40 to +125 degC, 8-pin SOIC (D), Green (RoHS & no Sb/Br)	D0008A	UCC2808AQDR-1Q1	Texas Instruments
U2	1		Opto-Isolator, 1 Channel, SMT	DIP-4	LTV-817S	Lite-On
U3	1		PRECISION PROGRAMMABLE REFERENCE, DBZ0003A	DBZ0003A	TL431AIDBZ	Texas Instruments

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